

	Type	Hits	Search Text	DBs
1	BRS	11054	alignment near mark	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	661	257/797	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	97	257/797 and align\$5 near (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	564	257/797 not (257/797 and align\$5 near (layers or films))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	66	257/797 and align\$5 near (layers or films) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	0	257/797 and (align\$5 near (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	6	alignment near mark and (align\$5 near (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	31	alignment near mark and ( (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	0	5817242.pn. and alignment near mark and ( (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; JPO
10	BRS	1	5817242.pn.	USPAT; JPO
11	BRS	1.	5817242.pn. and alignment near mark	USPAT; JPO
12	BRS	0	5817242.pn. and alignment near mark and ( (layers or films) near (back))	USPAT; JPO

	Type	Hits	Search Text	DBs
13	BRS	1	5817242.pn. and alignment near mark and ( (layers or films) ) and (integrated near circuit or IC)	USPAT; JPO
14	BRS	1569	alignment near mark and ( (layers or films) ) and (integrated near circuit or IC)	USPAT; JPO
15	BRS	11	(alignment near mark near (first near surface)) and ( (layers or films) ) and (integrated near circuit or IC)	USPAT; JPO
16	BRS	182	(alignment near mark near (first or front)) and ( (layers or films) ) and (integrated near circuit or IC)	USPAT; JPO
17	BRS	66	(alignment near mark near (first or front)) and ( (layers or films) near (second or back or opposite)) and (integrated near circuit or IC)	USPAT; JPO
18	BRS	17	(alignment near mark near (first or front or top)) and ( (layers or films) near (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
19	BRS	36	(alignment near mark with (first or front or top) near surface) and ( (layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
20	BRS	0	(alignment near mark with (first or front or top) near surface) and ( receiv\$3 with (layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
21	BRS	28	(alignment near mark with (first or front or top) near surface) and ( form\$3 with (layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO

	Type	Hits	Search Text	DBs
22	BRS	3	(alignment near mark with (first or front or top) near surface) and ( form\$3 with (integrated near circuit or IC) with (second or back or opposite or bottom) near surface)	USPAT; JPO
23	BRS	0	6309943.pn. and (alignment near mark) and printed and recess	USPAT; JPO
24	BRS	1	6309943.pn. and (alignment near mark) and printed	USPAT; JPO
25	BRS	4	(alignment near mark) near printed near substrate	USPAT; JPO
26	BRS	7	61156839.pn. or 5952247.pn. or 6013954.pn. or 5952694.pn. or 5754405.pn. or 6309943.pn. or 4423127.pn.	USPAT; JPO
27	BRS	154	257/798	USPAT
28	BRS	380	257/798	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB